



Material Content Data Sheet



Sales Product Name		BSZ130N03MS G		Issued		29. August 2013		
MA#		MA000896774						
Package		PG-TSDSON-8-21		Weight*		35.91 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.531	1.48	1.48	14781	14781
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		66	
	non noble metal	zinc	7440-66-6	0.009	0.03		264	
	non noble metal	iron	7439-89-6	0.189	0.53		5274	
	non noble metal	copper	7440-50-8	7.689	21.41	21.98	214135	219739
	noble metal	gold	7440-57-5	0.086	0.24	0.24	2403	2403
wire	noble metal	gold	7440-57-5	0.086	0.24	0.24	2403	2403
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1054	
	plastics	epoxy resin	-	1.950	5.43		54303	
	inorganic material	silicondioxide	60676-86-0	16.943	47.18	52.72	471857	527214
	non noble metal	tin	7440-31-5	0.370	1.03	1.03	10306	10306
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2250	2250
solder	non noble metal	tin	7440-31-5	0.042	0.12		1166	
	non noble metal	lead	7439-92-1	0.796	2.22	2.34	22157	23323
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		131	
	non noble metal	iron	7439-89-6	0.094	0.26		2617	
	non noble metal	copper	7440-50-8	3.816	10.63	10.90	106273	109054
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		109	
	non noble metal	iron	7439-89-6	0.078	0.22		2182	
	non noble metal	copper	7440-50-8	3.182	8.86	9.09	88612	90930
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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